

# N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}$ (m $\Omega$ )(Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)				
40	8.2 at $V_{GS} = 10 \text{ V}$	48	39.8 nC				
40	12 at V <sub>GS</sub> = 4.5 V	40					

#### **FEATURES**



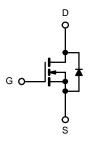
- DT-Trench Power MOSFET
- 100 % Rg and UIS tested
- AEC-Q101 Qualified for Automotive Applications

#### **APPLICATIONS**

- · Notebook PC Core
- VRM/POL

### **DFN5X6-8L Pin Configuration**





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V <sub>DS</sub>	40	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Dunin Comment /T 475 90\2	T <sub>C</sub> = 25 °C	,	48	Α		
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>a</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	39			
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	160				
Single Avalanche Energy		E <sub>AS</sub>	40	mJ		
Maximum Power Dissipation <sup>c</sup>	T <sub>C</sub> = 25 °C	В	60	W		
waximum Fower Dissipation*	T <sub>C</sub> = 100 °C	P <sub>D</sub>	30	VV		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) d	R <sub>thJA</sub>	65	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.5			

#### Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R<sub>8JA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$			-	-	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>			-	2.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40  V$ , $V_{GS} = 0  V$	-	-	1	μA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 32 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	48	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A	-	8.2	9.9		
Diani-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A	-	12	14	mΩ	
Forward Transconductancea	rd Transconductance <sup>a</sup> $g_{fs}$ $V_{DS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		-	110	-	S	
Dynamic <sup>b</sup>			•	•			
Input Capacitance	C <sub>iss</sub>		-	2000	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	-	152	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	123	-		
Total Gate Charge <sup>c</sup>	Qg		-	39.8	-		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub> V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 10 V,		-	3.84	-	nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	6.45	-		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	-	2	-	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	20	-		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 0.555 \Omega,$	-	15	-		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$R\text{GEN} = 1\Omega,V\text{GS} = 10V,I_D = 20A$	-	70	-	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>		-	11	-		
<b>Drain-Source Body Diode Ratings and</b>	Characterist	ics <sup>b</sup> (T <sub>J</sub> = 25 °C)					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	48	Α	
Pulsed Current	I <sub>SM</sub>		-	-	160	Α	
Forward Voltage <sup>a</sup> $V_{SD}$ $I_F = 1$		I <sub>F</sub> = 1 A, V <sub>GS</sub> = 0 V	-	0.8	-	V	
Reverse Recovery Time	t <sub>rr</sub>	L_ = 20 A di/dt = 400 A/uc	-	53	-	ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	-	71	-	nC	

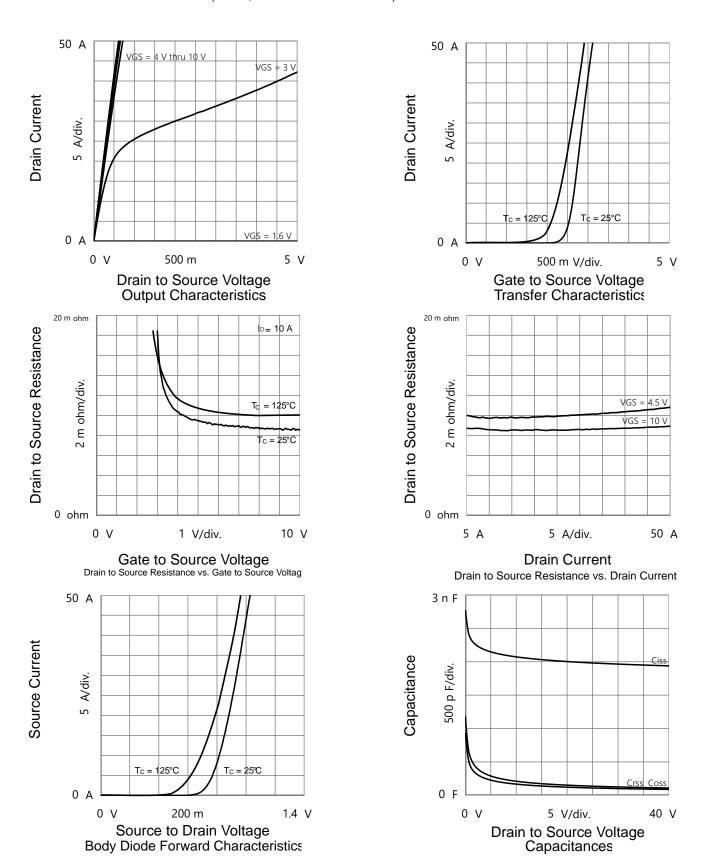
#### **Notes**

- a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those in dicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended pe riods may affect device reliability.

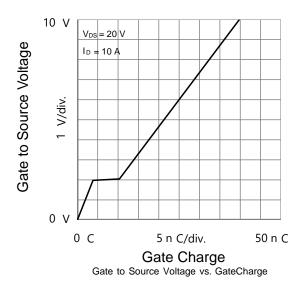


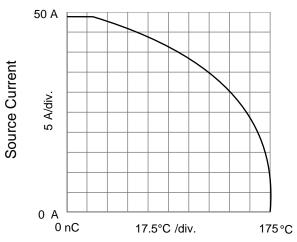
### TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)



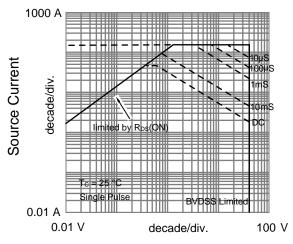


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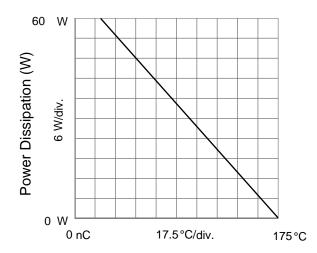




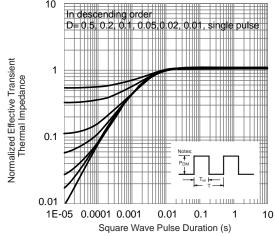
T<sub>C</sub> - Case Temperature



Source to Drain Voltage Safe Operating Area, Junction-to-Case



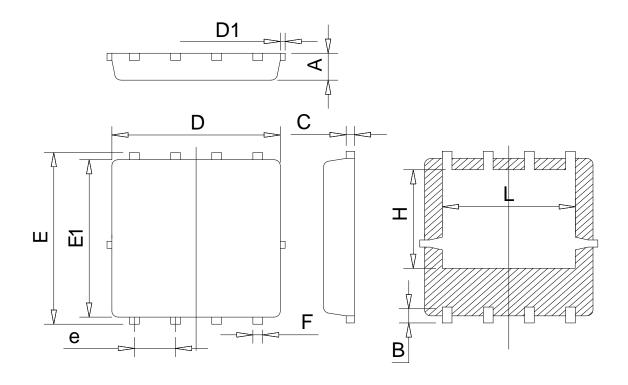
T<sub>C</sub> - Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



### DFN5X6-8L PACKAGE OUTLINE



## **COMMON DIMENSIONS** (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
Α	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
е	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25





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